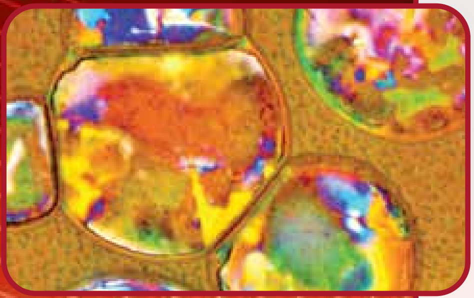
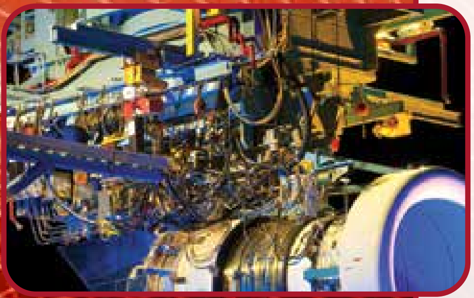
JOM

Call for papers

An official publication of The Minerals, Metals & Materials Society





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Manuscript Deadline: *November 1, 2024*

Localized Mechanical Property Assessment in Electronic Materials and Systems

Electronic devices found in consumer electronics, high performance computing, or power electronics are enabled by material science advances. In order to further advance computing power, new challenges in packaging, chiplet design, and power delivery need to be addressed. Thermal and mechanical properties in the chip ecosystem are key elements that must be understood and characterized. Nanomechanical testing and characterization are needed to ensure reliable performance of these systems. We invite papers featuring mechanical as well as combined tests (thermal-mechanical, electrical-mechanical, etc.) and evaluations of materials and composites relevant for electronic applications.

Original research papers should be 3,000-9,000 words with up to 12 figures maximum; review papers should be 6,000-11,000 words with up to 20 figures maximum.

Detailed author instructions are available at:
http://www.tms.org/AuthorTools/

Keywords for this topic: **Electronic Materials; Mechanical Properties; Surface Modification and Coatings; Synthesis and Processing; Thin Films and Interfaces**

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Committee Sponsor(s): **Nanomechanical Materials Behavior; Electronic Packaging and Interconnection Materials**

If you are interested in submitting a paper, upload your manuscript at **https://www.editorialmanager.com/jomj/**

Please note that all submissions will be subject to peer review. Submission does not guarantee acceptance.

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